

MEGIC-01-013



February 25, 2002

GP/2811
#2/205
6/27/2
Sunder

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/054,001 01/19/02

Mou-Shiung Lin et al.

THIN FILM SEMICONDUCTOR PACKAGE
AND METHOD OF FABRICATION

Grp. Art Unit: 2811

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner of Patents and
Trademarks, Washington, D.C. 20231, on March 1, 2002.

Stephen B. Ackerman, Reg.# 37761

Signature/Date Stephen B Ackerman 3/1/02

The following two publications relate to the use of thin films in the interconnection and packaging of semiconductor dies:

- 1) Microelectronic Packaging Handbook, Chapter 9, R.R. Tummala et al., Van Nostrand Reinhold, NY, 1989, pp. 673-725.
- 2) Novel Microelectronic Packaging Method for Reduced Thermomechanical Stresses on Low Dielectric Constant Materials, R.M. Emery et al., Intel Corp., Chandler, AZ.

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761